

WHAT IS CLAIMED IS:

1        1. A process for cleaning paste residue from a workpiece  
2        comprising the step of electrolytically contacting the  
3        workpiece with an aqueous solution containing 0.2 to 2 weight  
4        percent TMAH.

1        2. The process of claim 1 wherein the step of  
2        electrolytically contacting comprises spraying the workpiece  
3        with the aqueous solution.

1        3. The process of claim 1 wherein the step of  
2        electrolytically contacting comprises immersing the workpiece  
3        in the aqueous solution.

1        4. The process of claim 1 wherein the aqueous solution in the  
2        step of electrolytically contacting is maintained at a  
3        temperature of 25 to 80 °C.

1        5. The process of claim 1 wherein the aqueous solution in the  
2        step of electrolytically contacting is maintained at a  
3        temperature of 70 °C.

1 6. The process of claim 1 wherein the aqueous solution in the  
2 step of electrolytically contacting contains 0.4 to 0.5 weight  
3 percent TMAH.

1 7. The process of claim 1 further comprising the step, prior  
2 to the step of electrolytically contacting, of  
3 nonelectrolytically contacting the workpiece with an aqueous  
4 solution containing 0.2 to 2 weight percent TMAH.

1 8. The process of claim 7 wherein the step of  
2 nonelectrolytically contacting comprises spraying the  
3 workpiece with the aqueous solution.

1 9. The process of claim 7 wherein the step of  
2 nonelectrolytically contacting comprises immersing the  
3 workpiece in the aqueous solution.

1 10. The process of claim 7 wherein the aqueous solution in  
2 the step of nonelectrolytically contacting is maintained at a  
3 temperature of 25 to 80 °C.

1 11. The process of claim 7 wherein the aqueous solution in  
2 the step of nonelectrolytically contacting is maintained at a  
3 temperature of 70 °C.

1 12. The process of claim 1 wherein the workpiece is a  
2 screening mask.

1 13. The process of claim 1 wherein the paste comprises  
2 solder.

1 14. The process of claim 1 wherein the paste comprises at  
2 least one metal selected from the group consisting of  
3 molybdenum, copper, tungsten, nickel, gold, palladium,  
4 platinum and silver.

1 15. The process of claim 1 wherein the paste residue  
2 comprises an inorganic material selected from the group  
3 consisting of ceramic and glass.

1 16. The process of claim 1 wherein the paste comprises a  
2 polymeric binder.